# Silicon N-Channel MOS FET

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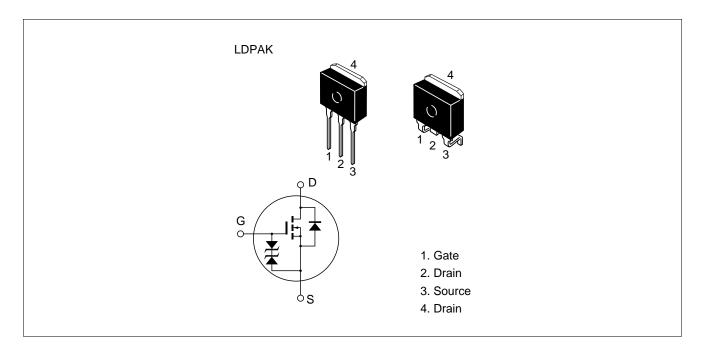
#### Application

High speed power switching

#### Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

#### Outline





### Absolute Maximum Ratings (Ta = $25^{\circ}$ C)

Item		Symbol	Ratings	Unit
Drain to source voltage 2SK1313		V <sub>DSS</sub>	450	V
	2SK1314		500	
Gate to source voltage		V <sub>GSS</sub>	±30	V
Drain current		I <sub>D</sub>	5	A
Drain peak current		l ★1 D(pulse)	20	A
Body to drain diode reverse	e drain current	I <sub>DR</sub>	5	A
Channel dissipation		Pch*2	50	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at  $T_c = 25^{\circ}C$ 

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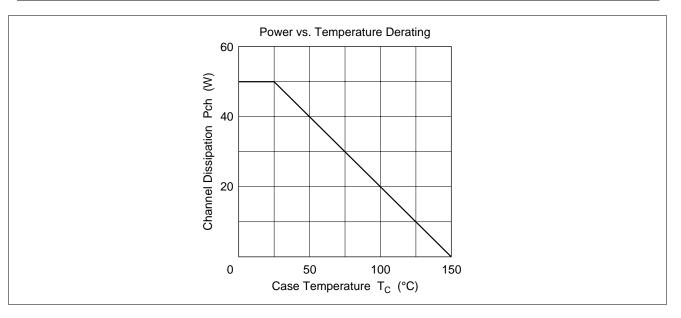
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#### **Electrical Characteristics** (Ta = 25°C)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1313	$V_{(BR)DSS}$	450	_	_	V	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = 0$
breakdown voltage	2SK1314	-	500	_			
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	_	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1313	I <sub>DSS</sub>	_	_	250	μA	$V_{\rm DS} = 360 \ V, \ V_{\rm GS} = 0$
drain current	2SK1314	-					$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0$
Gate to source cutoff	voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static Drain to source	2SK1313	$R_{DS(on)}$	_	1.0	1.4	Ω	$I_{\rm D}$ = 2.5 A, $V_{\rm GS}$ = 10 V * <sup>1</sup>
on state resistance	2SK1314	-	—	1.2	1.5		
Forward transfer admittance		yfs	2.5	4.0	—	S	$I_{\rm D}$ = 2.5 A, $V_{\rm DS}$ = 10 V * <sup>1</sup>
Input capacitance		Ciss	—	640	—	pF	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0,$
Output capacitance		Coss	—	160	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss	—	20	—	pF	_
Turn-on delay time		t <sub>d(on)</sub>	—	10	—	ns	$I_{\rm D}$ = 2.5 A, $V_{\rm GS}$ = 10 V,
Rise time		t,		25	—	ns	$R_{L} = 12 \Omega$
Turn-off delay time		t <sub>d(off)</sub>	_	50	—	ns	_
Fall time		t <sub>f</sub>	_	30	—	ns	_
Body to drain diode for voltage	orward	$V_{\text{DF}}$	_	0.95	_	V	$I_{F} = 5 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time		t <sub>rr</sub>	—	300	—	ns	$I_{F} = 5 \text{ A}, V_{GS} = 0,$ $di_{F}/dt = 100 \text{ A}/\mu\text{s}$
Note: 1. Pulse test							

See characteristic curves of 2SK1155, 2SK1156.

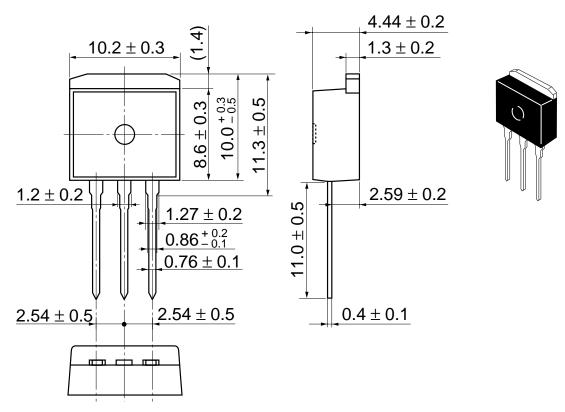
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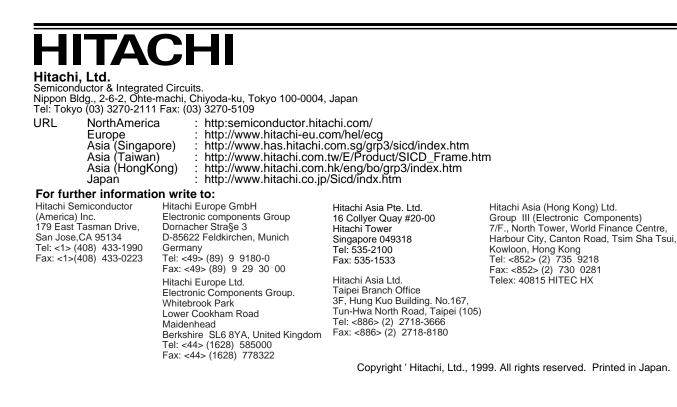
Unit: mm



Hitachi Code	LDPAK (L)			
JEDEC				
EIAJ				
Weight (reference value)	1.4 g			

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